

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A solar cell comprising an electrode coated with lead-free solder;

wherein said electrode is formed of fired metal paste; and

wherein said metal paste contains powdery silver, powdery glass, an organic vehicle, an organic solvent, phosphorous oxide, and halide.

2. (Cancelled)

3. (Currently Amended) The solar cell of claim 1, wherein one ~~any~~ technique of metal vapor deposition, sputteringspattering, and plating is used to coat ~~provide~~ said electrode.

4. (Original) The solar cell of claim 1, wherein said lead-free solder is one of Sn-Bi-Ag-based solder and Sn-Ag-based solder.

5. (Cancelled)

6. (Original) A solar cell comprising an electrode coated with lead-free solder after said electrode is cleaned with flux including resin, a solvent, and a stabilizer for resin;

wherein said electrode is formed of fired metal paste; and

wherein said metal paste contains powdery silver, powdery glass, an organic vehicle, an organic solvent, phosphorous oxide, and halide.

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7. (Original) An interconnector for solar cells, comprising a metal core coated with lead-free solder;

wherein said electrode is formed of fired metal paste; and  
wherein said metal paste contains powdery silver, powdery glass, an organic vehicle, an  
organic solvent, phosphorous oxide, and halide.

8. (Currently Amended) A solar cell string comprising solar cells including electrodes interconnected with interconnectors, wherein said electrodes each are each coated with lead-free solder and said interconnectors each are each also coated with lead-free solder;

wherein said electrode is formed of fired metal paste; and  
wherein said metal paste contains powdery silver, powdery glass, an organic vehicle, an  
organic solvent, phosphorous oxide, and halide.

9. (Original) The solar cell string of claim 8, wherein said lead-free solder used for said solar cell and said lead-free solder used for said interconector are identical in composition.

10. (Currently Amended) The string of claim 9, wherein Bi is contained in both ~~at least one of~~ said lead-free solder for said solar cell and said lead-free solder for said interconnector.

11. (Original) The solar cell of claim 4, wherein said lead-free solder contains 3 to 89 mass % Bi.

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12. (Original) The string of claim 10, wherein said lead-free solder contains 3 to 89 mass % Bi.

13. (Original) The string of claim 8, wherein Ag is contained in at least one of said lead-free solder for said solar cell and said lead-free solder for said interconnector.

14. (Original) The solar cell of claim 4, wherein said lead-free solder contains 3.5 to 4.5 mass % Ag.

15. (Original) The string of claim 13, wherein said lead-free solder contains 3.5 to 4.5 mass % Ag.

16. (New) A method of forming a solar cell having an electrode, comprising the steps of:

forming said electrode,

cleaning said electrode with flux including a resin, a solvent, and a stabilizer for said resin, and

coating said cleaned electrode with lead-free solder.